

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|--|------------------|---------|---------------------|
| L3 | 1 | (producing packaged integrated circuit comprising building least one micro-structure suspended above micro-cavity heating element capable itself immediate surroundings depositing layer protective).clm. | US-PGPUB; USPAT; USOCR; DERWENT | AND | ON | 2008/09/29 21:45 |

9/ 29/ 2008 9:45:44 PM

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